

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT2981965

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the APPLICATION NUMBER FROM 13/875,689 TO 13/875,659 (DOCUMENT ID NO. 502865873) previously recorded on Reel 030337 Frame 0795. Assignor(s) hereby confirms the ASSIGNMENT.
CONVEYING PARTY DATA	
Name	Execution Date
TZU-HSUAN HSU	04/09/2008
HAN-CHI LIU	04/09/2008
CHING-CHUN WANG	04/09/2008
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO. 8, LI-HSIN RD. 6
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13875659
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	214-651-5000
Email:	ipdocketing@haynesboone.com
Correspondent Name:	HAYNES AND BOONE, LLP IP SECTION
Address Line 1:	2323 VICTORY AVENUE
Address Line 2:	SUITE 700
Address Line 4:	DALLAS, TEXAS 75219
ATTORNEY DOCKET NUMBER:	24061.2520
NAME OF SUBMITTER:	DENISE M. WILSON
SIGNATURE:	/Denise M. Wilson/
DATE SIGNED:	08/14/2014
Total Attachments: 9	

PATENT

source=assignment#page1.tif
source=assignment#page2.tif
source=assignment#page3.tif
source=assignment#page4.tif
source=assignment#page5.tif
source=assignment#page6.tif
source=assignment#page7.tif
source=assignment#page8.tif
source=assignment#page9.tif

502333218 05/02/2013

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Tzu-Hsuan Hsu</td> <td>04/09/2008</td> </tr> <tr> <td>Han-Chi Liu</td> <td>04/09/2008</td> </tr> <tr> <td>Ching-Chun Wang</td> <td>04/09/2008</td> </tr> </tbody> </table>		Name	Execution Date	Tzu-Hsuan Hsu	04/09/2008	Han-Chi Liu	04/09/2008	Ching-Chun Wang	04/09/2008				
Name	Execution Date												
Tzu-Hsuan Hsu	04/09/2008												
Han-Chi Liu	04/09/2008												
Ching-Chun Wang	04/09/2008												
RECEIVING PARTY DATA													
<table border="1"> <tr> <td>Name:</td> <td>Taiwan Semiconductor Manufacturing Company, Ltd.</td> </tr> <tr> <td>Street Address:</td> <td>No. 8, Li-Hsin Rd. 6</td> </tr> <tr> <td>Internal Address:</td> <td>Science-Based Industrial Park</td> </tr> <tr> <td>City:</td> <td>Hsin-Chu</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300-77</td> </tr> </table>		Name:	Taiwan Semiconductor Manufacturing Company, Ltd.	Street Address:	No. 8, Li-Hsin Rd. 6	Internal Address:	Science-Based Industrial Park	City:	Hsin-Chu	State/Country:	TAIWAN	Postal Code:	300-77
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.												
Street Address:	No. 8, Li-Hsin Rd. 6												
Internal Address:	Science-Based Industrial Park												
City:	Hsin-Chu												
State/Country:	TAIWAN												
Postal Code:	300-77												
PROPERTY NUMBERS Total: 1													
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13875689</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13875689								
Property Type	Number												
Application Number:	13875689												
CORRESPONDENCE DATA													
<p>Fax Number: 2142000853</p> <p><i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 214-651-5000</p> <p>Email: ipdocketing@haynesboone.com</p> <p>Correspondent Name: Haynes and Boone, LLP.</p> <p>Address Line 1: 2323 Victory Avenue</p> <p>Address Line 2: Suite 700</p> <p>Address Line 4: Dallas, TEXAS 75219</p>													
ATTORNEY DOCKET NUMBER:	2007-0717-D / 24061.2520												
NAME OF SUBMITTER:	Kyle L. Howard												
Signature:	/Kyle L. Howard/												

OP \$40.00 13875689

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|-----------------|----|---|
| (1) | Tzu-Hsuan Hsu | of | No. 72, Gangshan Central St., Cianjhen District
Kaohsiung City 806, Taiwan, R.O.C. |
| (2) | Han-Chi Liu | of | No. 26, Fusin Village, Dahu Shiang
Miaoli County 364, Taiwan, R.O.C. |
| (3) | Ching-Chun Wang | of | 3F-1, No. 28, Lane 158, Sec. 2, Dongmen Rd.
Tainan, Taiwan, R.O.C. |

have invented certain improvements in

BACKSIDE DEPLETION FOR BACKSIDE ILLUMINATED IMAGE SENSORS

for which we have executed an application for Letters Patent of the United States of America,

 of even date filed herewith; and
 X filed on April 22, 2008 and assigned application number 12/107,199; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

Docket No.: 2007-0717CIP / 24061.993
Customer No.: 42717

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Tzu-Hsuan Hsu

Residence Address: No. 72, Gangshan Central St., Cianjhen District
Kaohsiung City 306, Taiwan, R.O.C.

Dated: Apr. 9, 2008

Tzu-Hsuan Hsu
Inventor Signature

Inventor Name: Han-Chi Liu

Residence Address: No. 26, Fusin Village, Dahu Shiang
Miaoli County 364, Taiwan, R.O.C.

Dated: Apr. 9, 2008

Han-Chi Liu
Inventor Signature

Inventor Name: Ching-Chun Wang

Residence Address: 3F-1, No. 28, Lane 158, Sec. 2, Dongmen Rd.
Tainan, Taiwan, R.O.C.

Dated: Apr. 9, 2008

Ching-Chun Wang
Inventor Signature